



LPAF-20-03.5-L-06-2-K

LPAF-20-03.5-L-04-2-K

(1.27 mm) .050"

LPAF SERIES

HIGH-SPEED LOW-PROFILE OPEN-PIN-FIELD

SPECIFICATIONS

Insulator Material:
Black LCP
Contact Material:
Copper Alloy
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Current Rating:
2.2 A per pin
(6 adjacent pins powered)
Working Voltage:
250 VAC
RoHS Compliant:
Yes
Lead-Free Solderable:
Yes

Mates with:
LPAM
Standoffs:
JSO, SO

RECOGNITIONS

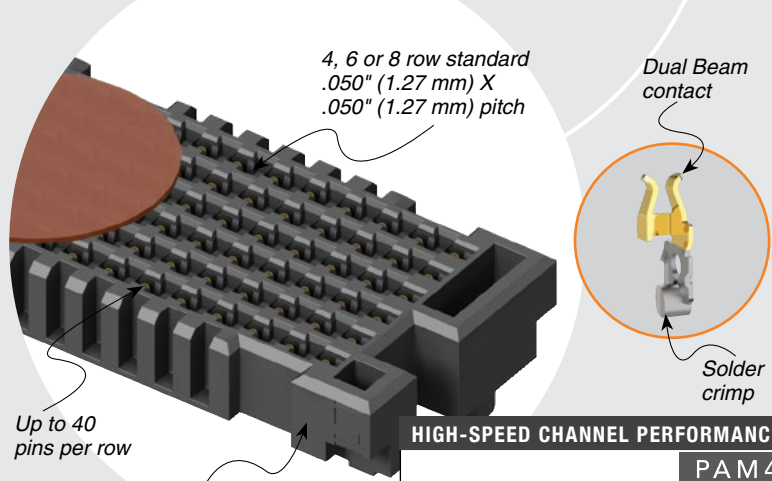


FILE NO. E111594

POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions



4, 6 or 8 row standard
.050" (1.27 mm) X
.050" (1.27 mm) pitch

Dual Beam contact

Solder crimp

Up to 40 pins per row

4 mm, 4.5 mm and 5 mm stack heights

HIGH-SPEED CHANNEL PERFORMANCE

LPAM/LPAF @ 5 mm Mated Stack Height
Rating based on Samtec reference channel.

PAM 4

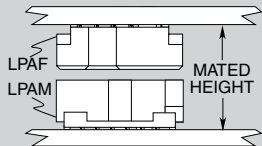
56 Gbps

ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
- Other pins/row and row counts
- Other Gold plating options

LPAF	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	K	TR
	-10, -20, -30, -40 (Per Row)	-03.0 = (3.0 mm) .118" -03.5 = (3.5 mm) .138"	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows -06 = Six Rows -08 = Eight Rows	-2 = Lead-Free Solder Crimp	-K = Polyimide film Pick & Place Pad	-TR = Tape & Reel

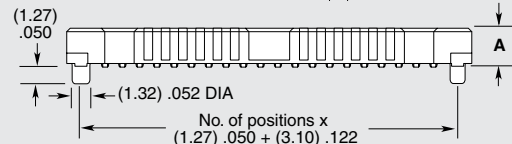
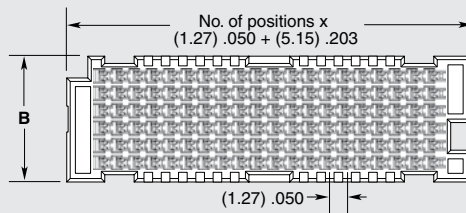
MATED HEIGHT



MATED HEIGHT*		
LPAF LEAD STYLE	LPAM LEAD STYLE	
	-01.0	-01.5
-03.0	(4.00) .157	(4.50) .177
-03.5	(4.50) .177	(5.00) .197

*Processing conditions will affect mated height.

NO. OF ROWS	B
-04	(6.71) .264
-06	(9.25) .364
-08	(11.79) .464



LEAD STYLE	A
-03.0	(2.79) .110
-03.5	(3.30) .130

Notes:

Patent Pending
Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.